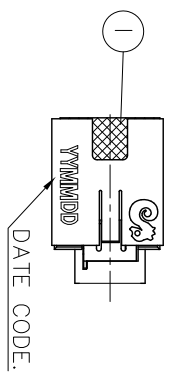
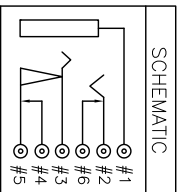


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PDR NO:1090720-3A	Tom	2009.07.21
B	ECN NO:S100152	Tom	2010.01.29
C	ECN NO:S100731	Swing	2010.07.29

- SPECIFICATIONS:
- INSULATION RESISTANCE BETWEEN ANY ADJACENT OPEN CIRCUIT TERMINAL SHELL NOT BE LESS THAN 100M Ω MEASURED BY 500 VDC MEGGER.
 - CONTACT RESISTANCE : 30m Ω MAX.
 - DIELECTRIC VOLTAGE WITHSTAND : 500V AC FOR ONE MINUTE.
 - UNLESS OTHERWISE SPECIFIED, TEST IS TO BE MADE AT 5-35°C IN TEMPERATURE AND 45-85% IN HUMIDITY. BUT,IF ANY VAGUE DATA IS OCCURED ON TEST RESULT, ANOTHER TEST SHALL BE MADE AT 20°C±2°C IN TEMP., 60-70% IN HUMIDITY.
 - LIFE TEST : 5,000 CYCLES MIN. (NON-LOAD)
 - INSERTION FORCE:0.4 - 3kg.
 - WITHDRAWAL FORCE:0.3 - 2kg.
 - AFTER LIFE TEST, CONTACT RESISTANCE: 50m Ω MAX.
 - AFTER HUMIDITY TEST, INSULATION RESISTANCE: 50M Ω MIN.
 - PACKAGING : TAPE & REEL.
 - TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
 - HALOGEN FREE PRODUCT IDENTIFICATION MARK ON JACK:Ⓞ
 - HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:
 - FOR REFLOW SOLDERING LEAD-FREE PROCESS.



NO	DESCRIPTION	QTY	MATERIAL	PLATING & COLOR
A	BODY	1	HIGH TEMP.THERMOPLASTIC	BLACK
B	SEPARATOR + TRANSFER TERMINAL	1	PHOSPHOR BRONZE 0.2t	ALL OVER 50μ" NICKEL PLATING. 1200" Sn PLATING ON SOLDER 1μ" Au PLATING ON CONTACT AREA
C	EARTH	1	COPPER ALLOY 0.3t	Ag 200" OVER IN 500" Min
D	TIP SPRING	1	PHOSPHOR BRONZE 0.25t	Ag 200" OVER IN 500" Min
E	RING SPRING	1	PHOSPHOR BRONZE 0.2t	Ag 200" OVER IN 500" Min
F	SHUNT TERMINAL-A	1	BRASS 0.25t	GOLD FLASH ON CONTACT AREA IN 500" Min
G	BREAK TERMINAL	1	BRASS 0.2t	ALL OVER 50μ" NICKEL PLATING. 1200" Sn PLATING ON SOLDER 1μ" Au PLATING ON CONTACT AREA
H	SHIELDING	1	SUS304 0.12T	金黃色
I	MYLAR	1	KAPTON+硅膠 0.06mmT	

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS: ANGLES:

X : ±0.5 X : ±2°
X.X : ±0.3 X.X : ±1'
X.XX : ±0.2

TITLE: 03.5 PHONE JACK

PART NO.: 2SJ-R820-S08

SCALE: 4/1 UNIT: mm

SIZE: A3 SHEET: 1 OF 1 REV:C

Singatron Enterprise Co., Ltd.
信音企業股份有限公司

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